

L Number	Hits	Search Text	DB	Time stamp
4	11212	MES or "manufacturing execution system"	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:36
5	22	(MES or "manufacturing execution system") same (in-line or inline or "in line")	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 20:17
6 169	1 55	"6173750".PN. (US-6337221-\$ or US-6553276-\$ or US-6363295-\$ or US-5907492-\$ or US-5915231-\$ or US-4915565-\$ or US-4759675-\$ or US-4685998-\$ or US-4627787-\$ or US-4627151-\$ or US-6124637-\$ or US-5985695-\$ or US-5859475-\$ or US-5844803-\$ or US-6256549-\$ or US-6677219-\$ or US-6551860-\$ or US-6521468-\$ or US-6507096-\$ or US-6372526-\$ or US-6217949-\$ or US-6174752-\$ or US-6045652-\$ or US-5985377-\$ or US-5750421-\$ or US-5565008-\$).did. or (US-4683644-\$ or US-6284566-\$ or US-6549821-\$ or US-6392286-\$ or US-6589801-\$ or US-6537848-\$ or US-6432752-\$ or US-6417028-\$ or US-6015722-\$ or US-5336931-\$ or US-6230719-\$ or US-6656768-\$ or US-6162661-\$ or US-5946553-\$ or US-5834336-\$ or US-5817545-\$ or US-5620927-\$ or US-6333210-\$ or US-6602430-\$ or US-6730545-\$ or US-6730532-\$).did. or (US-20010051394-\$ or US-20020082740-\$ or US-20030191550-\$ or US-20030003622-\$ or US-20010037568-\$ or US-20030093173-\$ or US-20030020509-\$ or US-20020181758-\$).did.	USPAT; USPAT; US_PGPUB	2004/11/03 20:20 2004/11/03 20:56
172	2	((US-6337221-\$ or US-6553276-\$ or US-6363295-\$ or US-5907492-\$ or US-5915231-\$ or US-4915565-\$ or US-4759675-\$ or US-4685998-\$ or US-4627787-\$ or US-4627151-\$ or US-6124637-\$ or US-5985695-\$ or US-5859475-\$ or US-5844803-\$ or US-6256549-\$ or US-6677219-\$ or US-6551860-\$ or US-6521468-\$ or US-6507096-\$ or US-6372526-\$ or US-6217949-\$ or US-6174752-\$ or US-6045652-\$ or US-5985377-\$ or US-5750421-\$ or US-5565008-\$).did. or (US-4683644-\$ or US-6284566-\$ or US-6549821-\$ or US-6392286-\$ or US-6589801-\$ or US-6537848-\$ or US-6432752-\$ or US-6417028-\$ or US-6015722-\$ or US-5336931-\$ or US-6230719-\$ or US-6656768-\$ or US-6162661-\$ or US-5946553-\$ or US-5834336-\$ or US-5817545-\$ or US-5620927-\$ or US-6333210-\$ or US-6602430-\$ or US-6730545-\$ or US-6730532-\$).did. or (US-20010051394-\$ or US-20020082740-\$ or US-20030191550-\$ or US-20030003622-\$ or US-20010037568-\$ or US-20030093173-\$ or US-20030020509-\$ or US-20020181758-\$).did.) and (MES or "manufacturing execution system")	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 20:56

173	4	((US-6337221-\$ or US-6553276-\$ or US-6363295-\$ or US-5907492-\$ or US-5915231-\$ or US-4915565-\$ or US-4759675-\$ or US-4685998-\$ or US-4627787-\$ or US-4627151-\$ or US-6124637-\$ or US-5985695-\$ or US-5859475-\$ or US-5844803-\$ or US-6256549-\$ or US-6677219-\$ or US-6551860-\$ or US-6521468-\$ or US-6507096-\$ or US-6372526-\$ or US-6217949-\$ or US-6174752-\$ or US-6045652-\$ or US-5985377-\$ or US-5750421-\$ or US-5565008-\$).did. or (US-4683644-\$ or US-6284566-\$ or US-6549821-\$ or US-6392286-\$ or US-6589801-\$ or US-6537848-\$ or US-6432752-\$ or US-6417028-\$ or US-6015722-\$ or US-5336931-\$ or US-6230719-\$ or US-6656768-\$ or US-6162661-\$ or US-5946553-\$ or US-5834336-\$ or US-5817545-\$ or US-5620927-\$ or US-6333210-\$ or US-6602430-\$ or US-6730545-\$ or US-6730532-\$).did. or (US-20010051394-\$ or US-20020082740-\$ or US-20030191550-\$ or US-20030003622-\$ or US-20010037568-\$ or US-20030093173-\$ or US-20030020509-\$ or US-20020181758-\$).did.) and (manag\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:28
174	544	(MES or "manufacturing execution system") same (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 20:58
175	1117	(MES or "manufacturing execution system") and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 22:02
176	602	(MES or "manufacturing execution system") and (semiconductor or wafer) and line	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 20:58
177	270	((MES or "manufacturing execution system") same (semiconductor or wafer)) and line	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 20:59
178	3	((MES or "manufacturing execution system") same (semiconductor or wafer)) and line and (camera or vision\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 20:59
181	2452	700/95,117,121,96.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:31

182	2	((US-6337221-\$ or US-6553276-\$ or US-6363295-\$ or US-5907492-\$ or US-5915231-\$ or US-4915565-\$ or US-4759675-\$ or US-4685998-\$ or US-4627787-\$ or US-4627151-\$ or US-6124637-\$ or US-5985695-\$ or US-5859475-\$ or US-5844803-\$ or US-6256549-\$ or US-6677219-\$ or US-6551860-\$ or US-6521468-\$ or US-6507096-\$ or US-6372526-\$ or US-6217949-\$ or US-6174752-\$ or US-6045652-\$ or US-5985377-\$ or US-5750421-\$ or US-5565008-\$).did. or (US-4683644-\$ or US-6284566-\$ or US-6549821-\$ or US-6392286-\$ or US-6589801-\$ or US-6537848-\$ or US-6432752-\$ or US-6417028-\$ or US-6015722-\$ or US-5336931-\$ or US-6230719-\$ or US-6656768-\$ or US-6162661-\$ or US-5946553-\$ or US-5834336-\$ or US-5817545-\$ or US-5620927-\$ or US-6333210-\$ or US-6602430-\$ or US-6730545-\$ or US-6730532-\$).did. or (US-20010051394-\$ or US-20020082740-\$ or US-20030191550-\$ or US-20030003622-\$ or US-20010037568-\$ or US-20030093173-\$ or US-20030020509-\$ or US-20020181758-\$).did.) and (host\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:37
183	1122	700/95,117,121,96;438/106,107,110-113,118,127 and @pd>=20040202	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:32
184	929	700/95,117,121,96;438/106,107,110-113,118,127 and @pd>=20040202 and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:32
185	576	700/95,117,121,96;438/106,107,110-113,118,127 and @pd>=20040202 and (semiconductor or wafer) and line	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:32
186	36	(MES or "manufacturing execution system") same (reject\$5 or "quality control")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:55
187	24	((US-6337221-\$ or US-6553276-\$ or US-6363295-\$ or US-5907492-\$ or US-5915231-\$ or US-4915565-\$ or US-4759675-\$ or US-4685998-\$ or US-4627787-\$ or US-4627151-\$ or US-6124637-\$ or US-5985695-\$ or US-5859475-\$ or US-5844803-\$ or US-6256549-\$ or US-6677219-\$ or US-6551860-\$ or US-6521468-\$ or US-6507096-\$ or US-6372526-\$ or US-6217949-\$ or US-6174752-\$ or US-6045652-\$ or US-5985377-\$ or US-5750421-\$ or US-5565008-\$).did. or (US-4683644-\$ or US-6284566-\$ or US-6549821-\$ or US-6392286-\$ or US-6589801-\$ or US-6537848-\$ or US-6432752-\$ or US-6417028-\$ or US-6015722-\$ or US-5336931-\$ or US-6230719-\$ or US-6656768-\$ or US-6162661-\$ or US-5946553-\$ or US-5834336-\$ or US-5817545-\$ or US-5620927-\$ or US-6333210-\$ or US-6602430-\$ or US-6730545-\$ or US-6730532-\$).did. or (US-20010051394-\$ or US-20020082740-\$ or US-20030191550-\$ or US-20030003622-\$ or US-20010037568-\$ or US-20030093173-\$ or US-20030020509-\$ or US-20020181758-\$).did.) and (central\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:37

196	38	(MES or "manufacturing execution system") same , (category\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 21:55
205	52	(MES or "manufacturing execution system") and (semiconductor or wafer) and (in-line or inline or "in line")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 22:03
206	57	(MES or "manufacturing execution system") and (semiconductor or wafer) and (in-line or inline or "in line" or "assembly line")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 22:40
230	8	CHANG-BO-SOON CHANG-BO-S	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/03 23:14
-	10	CHANG-BO-SOON CHANG-BO-S CHANG-BO-H CHANG-BO-E	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/01 15:50
-	869	700/121.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 18:22
-	25	700/121.cccls. and ("back-end" or "back end")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 16:18
-	2457	(die or chip or IC or wafer) and (cure or curing or cured) and bond\$9 and (plasma or clean\$6) and (encapsulat\$6 or mold\$8) and (dicing or diced or dice or saw\$6 or singulat\$8 or cut\$8) and (camera or vision or test\$6) and (convey\$6 or transport\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 18:59
-	0	700/121.cccls. and (die or chip or IC or wafer) and (cure or curing or cured) and bond\$9 and (plasma or clean\$6) and (encapsulat\$6 or mold\$8) and (dicing or diced or dice or saw\$6 or singulat\$8 or cut\$8) and (camera or vision or test\$6) and (convey\$6 or transport\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 12:48
-	24	((die or chip or IC or wafer) and (cure or curing or cured) and bond\$9 and (plasma or clean\$6) and (encapsulat\$6 or mold\$8) and (dicing or diced or dice or saw\$6 or singulat\$8 or cut\$8) and (camera or vision or test\$6) and (convey\$6 or transport\$6)) and line and ("back end" or "back-end")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 18:32
-	55	((die or chip or IC or wafer) and (cure or curing or cured) and bond\$9 and (plasma or clean\$6) and (encapsulat\$6 or mold\$8) and (dicing or diced or dice or saw\$6 or singulat\$8 or cut\$8) and (camera or vision or test\$6) and (convey\$6 or transport\$6)) and ("assembly line")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 19:00
-	0	700/121.cccls. and (die or chip or IC or wafer) and (cure or curing or cured) and bond\$9 and (plasma or clean\$6) and (encapsulat\$6 or mold\$8) and (dicing or diced or dice or saw\$6 or singulat\$8 or cut\$8) and (convey\$6 or transport\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 12:50

	0	700/121.cccls. and bond\$9 and (cure or cured or curing) and (plasma or clean\$6) and (encapsulat\$6 or mold\$8) and (convey\$6 or transport\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 13:00
	2	700/121.cccls. and bond\$9 and (plasma or clean\$6) and (encapsulat\$6 or mold\$8) and (convey\$6 or transport\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 13:05
	687	"strip die" or "strip-die"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 13:06
	185	700/96.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 14:00
	8282	438/106-127.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 16:35
	163	438/106-127.cccls. and (conveyor or conveyance or transporter)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 18:19
	100	700/230.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 15:25
	7	("3698076"   "4139726"   "5173766"   "5594234"   "5844803"   "5909053"   "5943558"   "2001/0041424"   "2002/0020929"   "2002/0031867"   "2002/0037604").PN.	USPAT	2004/01/30 18:02
	0	6521468.URPN.	USPAT	2004/01/30 18:10
	16	("2869053"   "3577633"   "3689991"   "3838984"   "4411719"   "4466183"   "4806409"   "4811081"   "4944850"   "4949155"   "4961984"   "5063434"   "5133118"   "5148266"   "5442229"   "5541451").PN.	USPAT	2004/01/30 18:10
	16	438/106-127.cccls. and (attach\$5) and (cure or cured or curing) and bond and (mold\$6 or encapsulat\$6) and (saw\$6 or singulat\$6) and test\$6 and sort\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/03 11:22
	71	(attach\$5) and (cure or cured or curing) and bond and (mold\$6 or encapsulat\$6) and (saw\$6 or singulat\$6) and test\$6 and sort\$6 and (conveyor or conveyance or transporter or conveyed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 19:29
	52	438/106.cccls. and (conveyor or conveyance or conveyed or transporter)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 19:42
	63	(wire near bond\$6) and (die near attach\$8) and singulat\$6 and (conveyor or conveyance or conveyed or transporter)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/30 19:43
	14	("4740247"   "5564159"   "5663593"   "5677569"   "5706178"   "5708567"   "5712570"   "5729050"   "5741729"   "5748450"   "5783220"   "5796170"   "5821613"   "6072233").PN.	USPAT	2004/01/30 20:06
	0	6392286.URPN.	USPAT	2004/01/30 20:09

-	418	438/112.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 15:56
-	339	438/106-127.ccls. and ("in-line" or "in line")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 17:27
-	39	438/106-127.ccls. and ("in-line" or "in line") and (plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 17:18
-	26	438/106-127.ccls. and ((plasma with clean\$6) same (attach or bond))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 17:20
-	119	ST-ASSEMBLY-TEST-SERVICES ST-ASSEMBLY-TEST-SERVICES-LIMI ST-ASSEMBLY-TEST-SERVICES-LTD ST-ASSEMBLY-TEST-SERVICES-PTE-LTD ST-ASSEMBLY-TEST-SERVICE-LTD ST-ASSEMBLY-TEST-SERVICES-PTE-LTD	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 17:20
-	49	(ST-ASSEMBLY-TEST-SERVICES ST-ASSEMBLY-TEST-SERVICES-LIMI ST-ASSEMBLY-TEST-SERVICES-LTD ST-ASSEMBLY-TEST-SERVICES-PTE-LTD ST-ASSEMBLY-TEST-SERVICE-LTD ST-ASSEMBLY-TEST-SERVICES-PTE-LTD) and (conveyor or conveyance or conveyed or transport\$9 or transfer\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 17:21
-	2	6230719.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 17:24
-	11	438/106-127.ccls. and (conveyor).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 17:29
-	161	438/106-127.ccls. and (conveyor or conveyance)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/02 14:50
-	4	438/106-127.ccls. and (conveyor or conveyance) same (plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 18:22
-	811	438/106-127.ccls. and integration	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 18:22
-	77	438/106-127.ccls. and (integration same line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/31 18:22
-	4	SONG-KONG-LAM	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/01 15:53



-	488	438/106-127;700/121.ccls. and (camera or vision\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/03 12:42
-	42	438/106-127;700/121.ccls. and ((camera or vision\$6) with line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/03 12:42